1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings†

Input Voltage	6.5V
Output Voltage	(-0.3V) to (V _{IN} + 0.3V)
Power Dissipation	Internally Limited (Note 6)
Maximum Voltage on Any F	PinV _{IN} +0.3V to -0.3V
Operating Temperature Ran	$_{ m lige}$ 40°C < $T_{ m J}$ < 125°C
Storage Temperature	65°C to +150°C

† **Note:** Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions above those indicated in the operation sections of the specifications is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

TC1072/TC1073 ELECTRICAL SPECIFICATIONS

Electrical Characteristics: Unless otherwise noted, $V_{IN} = V_{OUT} + 1V$, $I_L = 0.1$ mA, $C_L = 3.3$ μ F, $\overline{SHDN} > V_{IH}$, $T_A = +25$ °C. **Boldface** type specifications apply for junction temperatures of -40°C to +125°C.

Symbol	Parameter	Min	Тур	Max	Units	Test Conditions
V _{IN}	Input Operating Voltage	2.7	_	6.0	V	Note 9
I _{OUTMAX}	Maximum Output Current	50 100	_	_	mA mA	TC1072 TC1073
V _{OUT}	Output Voltage	V _R – 2.5%	V _R ±0.5%	V _R + 2.5%	V	Note 1
TCV _{OUT}	V _{OUT} Temperature Coefficient	_	20 40	_	ppm/°C	Note 2
$\Delta V_{OUT}/\Delta V_{IN}$	Line Regulation	_	0.05	0.35	%	$(V_R + 1V) \le V_{IN} \le 6V$
$\Delta V_{OUT}/V_{OUT}$	Load Regulation	_	0.5	2.0	%	I _L = 0.1 mA to I _{OUTMAX} (Note 3)
V _{IN} -V _{OUT}	Dropout Voltage	_ _ _	2 65 85 180	— — 120 250	mV	I _L = 0.1 mA I _L = 20 mA I _L = 50 mA I _L = 100 mA (Note 4), TC1073
I _{IN}	Supply Current	_	50	80	μA	$\overline{SHDN} = V_{IH}, I_L = 0 $ (Note 8)
I _{INSD}	Shutdown Supply Current	_	0.05	0.5	μΑ	SHDN = 0V
PSRR	Power Supply Rejection Ratio	_	64	_	dB	F _{RE} ≤1 kHz
I _{OUTSC}	Output Short Circuit Current	_	300	450	mA	V _{OUT} = 0V
$\Delta V_{OUT}/\Delta P_{D}$	Thermal Regulation	_	0.04	_	V/W	Notes 5, 6
T _{SD}	Thermal Shutdown Die Temperature	_	160	_	°C	
ΔT_{SD}	Thermal Shutdown Hysteresis	_	10	_	°C	
eN	Output Noise	_	260	_	nV/√Hz	I _L = I _{OUTMAX} 470 pF from Bypass to GND

Note 1: V_R is the regulator output voltage setting. For example: $V_R = 2.5V$, 2.7V, 2.85V, 3.0V, 3.3V, 3.6V, 4.0V, 5.0V.

- 3: Regulation is measured at a constant junction temperature using low duty cycle pulse testing. Load regulation is tested over a load range from 0.1 mA to the maximum specified output current. Changes in output voltage due to heating effects are covered by the thermal regulation specification.
- 4: Dropout voltage is defined as the input to output differential at which the output voltage drops 2% below its nominal value.
- 5: Thermal Regulation is defined as the change in output voltage at a time T after a change in power dissipation is applied, excluding load or line regulation effects. Specifications are for a current pulse equal to I_{LMAX} at V_{IN} = 6V for T = 10 ms.
- 6: The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature and the thermal resistance from junction-to-air (i.e., T_A, T_J, θ_{JA}). Exceeding the maximum allowable power dissipation causes the device to initiate thermal shutdown. Please see Section 5.0 "Thermal Considerations" for more details.
- 7: Hysteresis voltage is referenced by V_R
- 8: Apply for Junction Temperatures of -40°C to +85°C.
- 9: The minimum V_{IN} has to justify the conditions = $V_{IN} \ge V_R + V_{DROPOUT}$ and $V_{IN} \ge 2.7V$ for $I_L = 0.1$ mA to I_{OUTMAX} .

^{2:} $TC V_{OUT} = \frac{(V_{OUTMAX} - V_{OUTMIN}) \times 10^6}{V_{OUT} \times \Delta T}$

TC1072/TC1073 ELECTRICAL SPECIFICATIONS (CONTINUED)

Electrical Characteristics: Unless otherwise noted, $V_{IN} = V_{OUT} + 1V$, $I_L = 0.1$ mA, $C_L = 3.3$ μ F, $\overline{SHDN} > V_{IH}$, $T_A = +25$ °C. **Boldface** type specifications apply for junction temperatures of -40°C to +125°C.

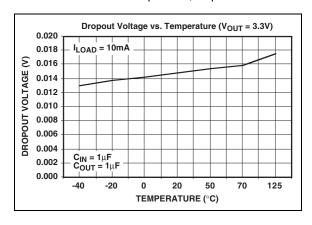
Symbol	Parameter	Min	Тур	Max	Units	Test Conditions
SHDN Input						
V _{IH}	SHDN Input High Threshold	45	_	1	%V _{IN}	V _{IN} = 2.5V to 6.5V
V _{IL}	SHDN Input Low Threshold	_	_	15	%V _{IN}	V _{IN} = 2.5V to 6.5V
ERROR Open Drain Output						
V _{INMIN}	Minimum V _{IN} Operating Voltage	1.0	_	_	V	
V _{OL}	Output Logic Low Voltage	_	_	400	mV	1 mA Flows to ERROR
V _{TH}	ERROR Threshold Voltage	_	0.95 x V _R	_	V	See Figure 4-2
V _{HYS}	ERROR Positive Hysteresis	_	50	_	mV	Note 7
t _{DELAY}	V _{OUT} to ERROR Delay	_	2.5	_	ms	Vout falling from V _R to V _R -10%

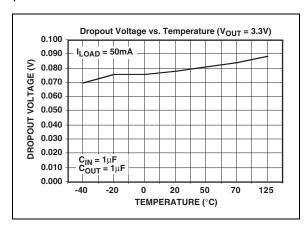
- Note V_R is the regulator output voltage setting. For example: V_R = 2.5V, 2.7V, 2.85V, 3.0V, 3.3V, 3.6V, 4.0V, 5.0V.
 - TC $V_{OUT} = (V_{OUTMAX} V_{OUTMIN}) \times 10^6$ V_{OUT} x ΔT
 - Regulation is measured at a constant junction temperature using low duty cycle pulse testing. Load regulation is tested over a load range from 0.1 mA to the maximum specified output current. Changes in output voltage due to heating effects are covered by the thermal
 - Dropout voltage is defined as the input to output differential at which the output voltage drops 2% below its nominal value.
 - Thermal Regulation is defined as the change in output voltage at a time T after a change in power dissipation is applied, excluding load or line regulation effects. Specifications are for a current pulse equal to I_{LMAX} at V_{IN} = 6V for T = 10 ms.
 - The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature and the thermal resistance from junction-to-air (i.e., T_A , T_J , θ_{JA}). Exceeding the maximum allowable power dissipation causes the device to initiate thermal shutdown. Please see **Section 5.0 "Thermal Considerations"** for more details.

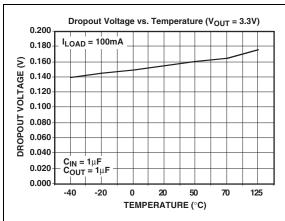
 - Hysteresis voltage is referenced by V_R . Apply for Junction Temperatures of -40 $^{\circ}$ C to +85 $^{\circ}$ C.
 - The minimum V_{IN} has to justify the conditions = $V_{IN} \ge V_R + V_{DROPOUT}$ and $V_{IN} \ge 2.7V$ for $I_L = 0.1$ mA to $I_{OUT_{MAX}}$.

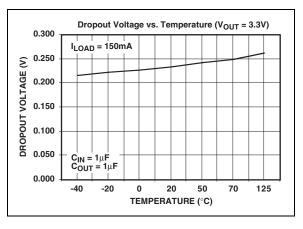
2.0 TYPICAL CHARACTERISTICS CURVES

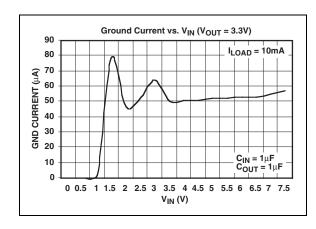
Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

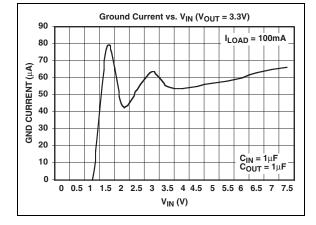


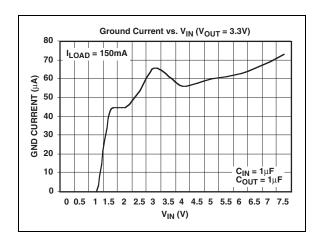


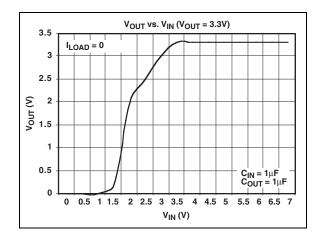


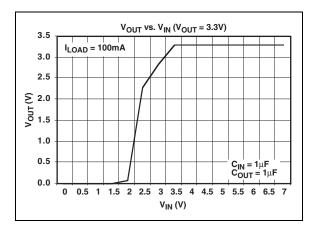


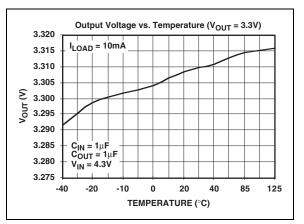


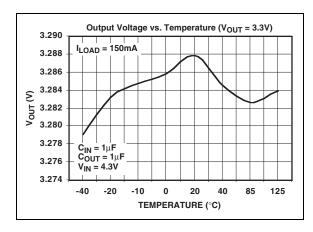


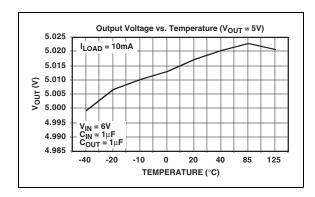


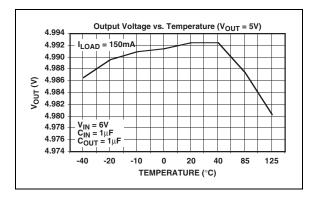


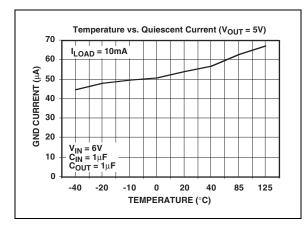


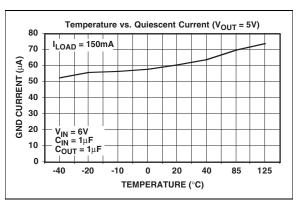


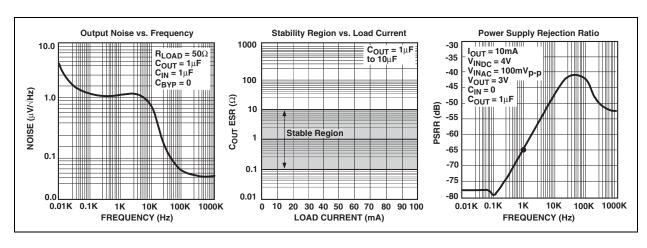


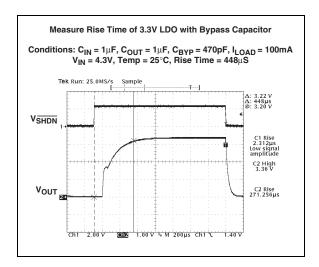


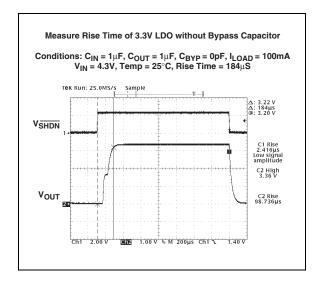


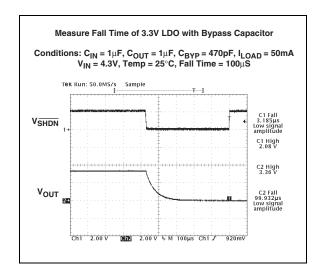


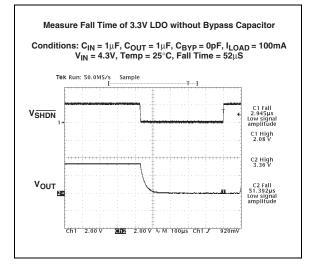


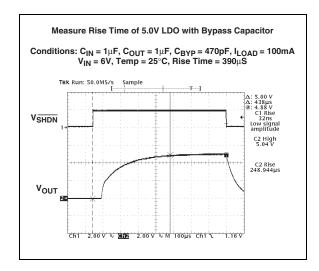


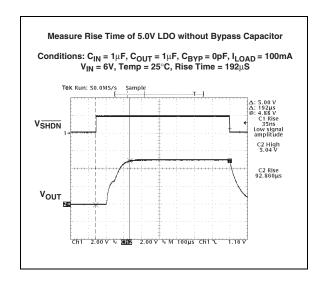


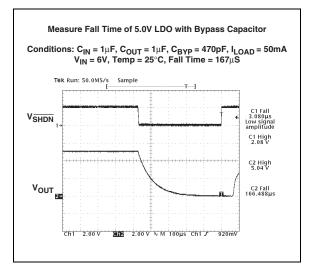


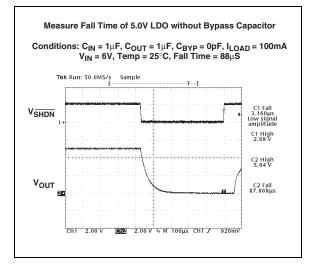


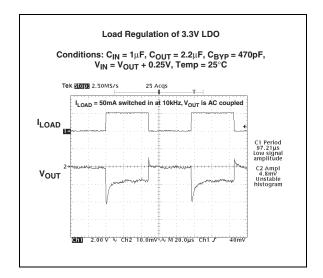


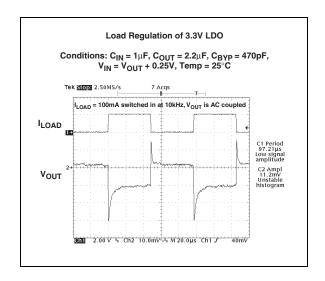


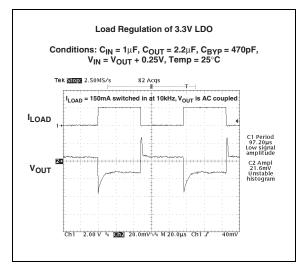


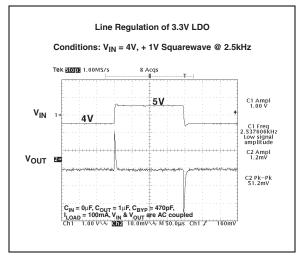


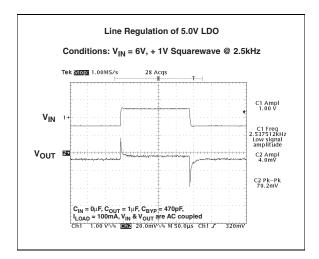


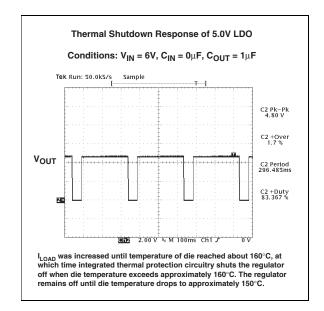












3.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 3-1.

TABLE 3-1: PIN FUNCTION TABLE

Pin No. (6-Pin SOT-23)	Symbol	Description
1	V _{IN}	Unregulated supply input.
2	GND	Ground terminal.
3	SHDN	Shutdown control input.
4	ERROR	Out-of-Regulation Flag. (Open drain output).
5	Bypass	Reference bypass input.
6	V _{OUT}	Regulated voltage output.

3.1 Input Voltage Supply (V_{IN})

Connect unregulated input supply to the V_{IN} pin. If there is a large distance between the input supply and the LDO regulator, some input capacitance is necessary for proper operation. A 1 μF capacitor connected from V_{IN} to ground is recommended for most applications.

3.2 Ground (GND)

Connect the unregulated input supply ground return to GND. Also connect the negative side of the 1 μ F typical input decoupling capacitor close to GND and the negative side of the output capacitor C_{OUT} to GND.

3.3 Shutdown Control Input (SHDN)

The regulator is fully enabled when a logic-high is applied to SHDN. The regulator enters shutdown when a logic-low is applied to \overline{SHDN} . During shutdown, output voltage falls to zero, \overline{ERROR} is open-circuited and supply current is reduced to 0.5 μA (maximum).

3.4 Out-Of-Regulation Flag (ERROR)

 $\overline{\text{ERROR}}$ goes low when V_{OUT} is out-of-tolerance by approximately – 5%.

3.5 Reference Bypass Input (Bypass)

Connecting a 470 pF to this input further reduces output noise.

3.6 Regulated Voltage Output (V_{OUT})

Connect the output load to V_{OUT} of the LDO. Also connect the positive side of the LDO output capacitor as close as possible to the V_{OUT} pin.

4.0 DETAILED DESCRIPTION

The TC1072 and TC1073 are precision fixed output voltage regulators. (If an adjustable version is desired, please see the TC1070/TC1071/TC1187 data sheet.) Unlike bipolar regulators, the TC1072 and TC1073's supply current does not increase with load current. In addition, $V_{\rm OUT}$ remains stable and within regulation over the entire 0 mA to $I_{\rm OUTMAX}$ load current range, (an important consideration in RTC and CMOS RAM battery back-up applications).

Figure 4-1 shows a typical application circuit. The regulator is enabled any time the shutdown input (SHDN) is at or above V_{IH} , and shutdown (disabled) when SHDN is at or below V_{IL} . SHDN may be controlled by a CMOS logic gate, or I/O port of a microcontroller. If the SHDN input is not required, it should be connected directly to the input supply. While in shutdown, supply current decreases to 0.05 μA (typical), V_{OUT} falls to zero volts, and ERROR is opencircuited.

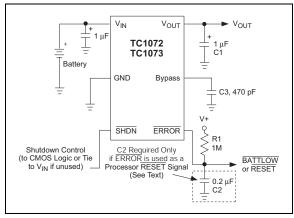


FIGURE 4-1: Typical Application Circuit.

4.1 ERROR Open-Drain Output

ERROR is driven low whenever V_{OUT} falls out of regulation by more than -5% (typical). This condition may be caused by low input <u>voltage</u>, output current limiting, or <u>thermal limiting</u>. The <u>ERROR</u> output voltage value (e.g. <u>ERROR</u> = V_{OL} at 4.75V (typical) for a 5.0V regulator and 2.85V (typical) for a 3.0V regulator). <u>ERROR</u> output operation is shown in <u>Figure 4-2</u>.

Note that ERROR is active tDELAY (typically, 2.5 $\mu s)$ after V_{OUT} falls to $V_{TH},$ and inactive when V_{OUT} rises above V_{TH} by $V_{HYS}.$

As shown in Figure 4-1, $\overline{\text{ERROR}}$ can be used as a battery low flag, or as a processor $\overline{\text{RESET}}$ signal (with the addition of timing capacitor C_2). $R_1 \times C_2$ should be chosen to maintain $\overline{\text{ERROR}}$ below V_{IH} of the processor $\overline{\text{RESET}}$ input for at least 200 ms to allow time for the system to stabilize. Pull-up resistor R_1 can be tied to V_{OUT} , V_{IN} or any other voltage less than $(V_{IN} + 0.3V)$.

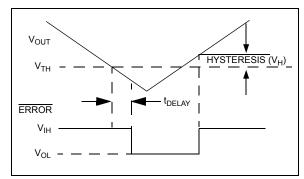


FIGURE 4-2: Error Output Operation.

4.2 Output Capacitor

A 1 μ F (minimum) capacitor from V_{OUT} to ground is recommended. The output capacitor should have an effective series resistance greater than 0.1Ω and less than 5.0 Ω , and a resonant frequency above 1 MHz. A 1 μ F capacitor should be connected from V_{IN} to GND if there is more than 10 inches of wire between the regulator and the AC filter capacitor, or if a battery is used as the power source. Aluminum electrolytic or tantalum capacitor types can be used. (Since many electrolytic capacitors freeze aluminum approximately -30°C, solid tantalums are recommended for applications operating below -25°C.) When operating from sources other than batteries, supply-noise rejection and transient response can be improved by increasing the value of the input and output capacitors and employing passive filtering techniques.

4.3 Bypass Input

A 470 pF capacitor connected from the Bypass input to ground reduces noise present on the internal reference, which in turn significantly reduces output noise. If output noise is not a concern, this input may be left unconnected. Larger capacitor values may be used, but results in a longer time period to rated output voltage when power is initially applied.

5.0 THERMAL CONSIDERATIONS

5.1 Thermal Shutdown

Integrated thermal protection circuitry shuts the regulator off when die temperature exceeds 160°C. The regulator remains off until the die temperature drops to approximately 150°C.

5.2 Power Dissipation

The amount of power the regulator dissipates is primarily a function of input and output voltage, and output current. The following equation is used to calculate worst-case *actual* power dissipation:

EQUATION 5-1:

$$P_D \approx (V_{INMAX} - V_{OUTMIN}) I_{LOADMAX}$$

Where:

P_D = Worst-case actual power dissipation

 V_{INMAX} = Maximum voltage on V_{IN}

V_{OUTMIN} = Minimum regulator output voltage

I_{LOADMAX} = Maximum output (load) current

The maximum allowable power dissipation (Equation 5-2) is a function of the maximum ambient temperature (T_{AMAX}), the maximum allowable die temperature (T_{JMAX}) and the thermal resistance from junction-to-air (θ_{JA}). The 6-Pin SOT-23 package has a θ_{JA} of approximately 220°C/Watt.

EQUATION 5-2:

$$P_{DMAX} = \underbrace{(T_{JMAX} - T_{AMAX})}_{\theta_{JA}}$$

where all terms are previously defined.

Equation 5-1 can be used in conjunction with Equation 5-2 to ensure regulator thermal operation is within limits. For example:

Given:

$$\begin{array}{ll} V_{\text{INMAX}} & = 3.0 \text{V} \pm 5\% \\ V_{\text{OUTMIN}} & = 2.7 \text{V} - 2.5\% \\ I_{\text{LOADMAX}} & = 40 \text{ mA} \\ T_{\text{JMAX}} & = 125^{\circ}\text{C} \\ T_{\text{AMAX}} & = 55^{\circ}\text{C} \end{array}$$

Find: 1. Actual power dissipation

2. Maximum allowable dissipation

Actual power dissipation:

$$P_D \approx (V_{INMAX} - V_{OUTMIN})I_{LOADMAX}$$

= $[(3.0 \times 1.05) - (2.7 \times 0.975)] \times 40 \times 10^{-3}$
= 20.7 mW

Maximum allowable power dissipation:

$$P_{DMAX} = \underbrace{(T_{JMAX} - T_{AMAX})}_{\theta_{JA}}$$

$$= \underbrace{(125 - 55)}_{220}$$

$$= 318 \text{ mW}$$

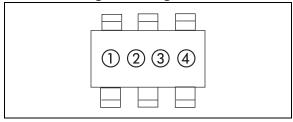
In this example, the TC1072 dissipates a maximum of 20.7 mW; below the allowable limit of 318 mW. In a similar manner, Equation 5-1 and Equation 5-2 can be used to calculate maximum current and/or input voltage limits.

5.3 Layout Considerations

The primary path of heat conduction out of the package is via the package leads. Therefore, layouts having a ground plane, wide traces at the pads, and wide power supply bus lines combine to lower θ_{JA} and therefore increase the maximum allowable power dissipation limit.

6.0 PACKAGING INFORMATION

6.1 Package Marking Information

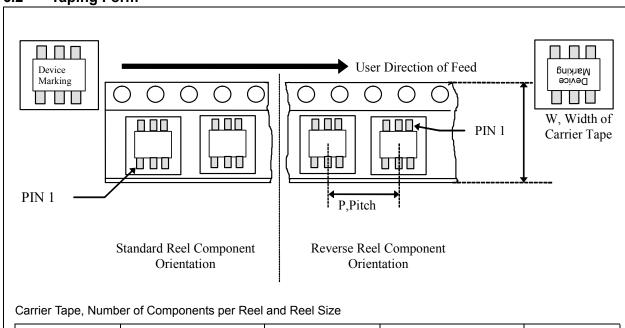


① & ② = part number code + threshold voltage (two-digit code)

(V)	TC1072 Code	TC1073 Code
1.8	EY	FY
2.5	E1	F1
2.6	ET	FT
2.7	E2	F2
2.8	EZ	FZ
2.85	E8	F8
3.0	E3	F3
3.3	E4	F4
3.6	E9	F9
4.0	E0	F0
5.0	E6	F6

- ③ represents year and quarter code
- 4 represents production lot ID code

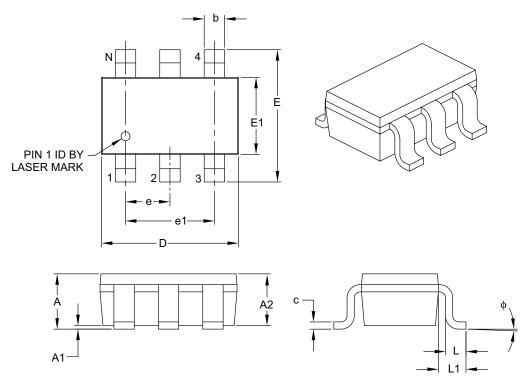
6.2 Taping Form



Package	Carrier Width (W)	Pitch (P)	Part Per Full Reel	Reel Size
6-Pin SOT-23	8 mm	4 mm	3000	7 in

6-Lead Plastic Small Outline Transistor (CH) [SOT-23]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	MILLIMETERS			
Dimen	sion Limits	MIN	NOM	MAX
Number of Pins	N		6	
Pitch	е		0.95 BSC	
Outside Lead Pitch	e1		1.90 BSC	
Overall Height	Α	0.90	_	1.45
Molded Package Thickness	A2	0.89	_	1.30
Standoff	A1	0.00	_	0.15
Overall Width	E	2.20	_	3.20
Molded Package Width	E1	1.30	_	1.80
Overall Length	D	2.70	_	3.10
Foot Length	L	0.10	_	0.60
Footprint	L1	0.35	_	0.80
Foot Angle	ф	0°	_	30°
Lead Thickness	С	0.08	_	0.26
Lead Width	b	0.20	_	0.51

Notes:

- 1. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.127 mm per side.
- 2. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-028B

NOTES:

APPENDIX A: REVISION HISTORY

Revision D (February 2007)

- Page 1: Ground current changed to 50 μA.
- Package type changed from SOT-23A to SOT-23.
- · Added voltage options.
- T_{DELAY} added to Table 1-1.
- Section 3.0 "Pin Descriptions": Added pin descriptions.
- Section 4.1 "ERROR Open-Drain Output": Defined t_{DELAY}.
- Changed Figure 4-2.
- · Updated Packaging Information.

Revision C (January 2006)

· Undocumented changes.

Revision B (May 2002)

· Undocumented changes.

Revision A (March 2002)

· Original Release of this Document.

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO. Device	— X.X X XXXXX	Examples: a) TC1072-1.8VCH713: 1.8V b) TC1072-2.5VCH713 2.5V c) TC1072-2.6VCH713 2.6V
Device	TC1072: CMOS LDO with Shutdown, ERROR Output & V _{REF} Bypass TC1073: CMOS LDO with Shutdown, ERROR Output & V _{REF} Bypass	d) TC1072-2.7VCH713 2.7V e) TC1072-2.8VCH713 2.8V f) TC1072-2.85VCH713 2.85V g) TC1072-3.0VCH713 3.0V h) TC1072-3.3VCH713 3.3V i) TC1072-3.6VCH713 3.6V j) TC1072-4.0VCH713 4.0V
Threshold voltage (typical)	1.8 = 1.8V 2.5 = 2.5V 2.6 = 2.6V 2.7 = 2.7V 2.8 = 2.8V 2.85 = 2.85V 3.0 = 3.0V 3.3 = 3.3V 3.6 = 3.6V 4.0 = 4.0V 5.0 = 5.0V	a) TC1072-5.0VCH713 5.0V a) TC1073-1.8VCH713: 1.8V b) TC1073-2.5VCH713 2.5V c) TC1073-2.6VCH713 2.6V d) TC1073-2.7VCH713 2.7V e) TC1073-2.8VCH713 2.8V f) TC1073-2.8VCH713 2.85V g) TC1073-3.0VCH713 3.0V h) TC1073-3.3VCH713 3.3V i) TC1073-3.6VCH713 3.6V
Temperature Range	V = -40° C to +125° C	j) TC1073-4.0VCH713 4.0V k) TC1073-5.0VCH713 5.0V
Package	CH713 = Plastic small outline transistor (CH) SOT-23, 6 lead, (tape and reel).	

NOTES:

Note the following details of the code protection feature on Microchip devices:

- · Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our
 knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data
 Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

Information contained in this publication regarding device applications and the like is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. MICROCHIP MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION, INCLUDING BUT NOT LIMITED TO ITS CONDITION, QUALITY, PERFORMANCE, MERCHANTABILITY OR FITNESS FOR PURPOSE. Microchip disclaims all liability arising from this information and its use. Use of Microchip devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless Microchip from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights.

Trademarks

The Microchip name and logo, the Microchip logo, Accuron, dsPIC, KEELOQ, KEELOQ logo, microID, MPLAB, PIC, PICmicro, PICSTART, PRO MATE, PowerSmart, rfPIC, and SmartShunt are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

AmpLab, FilterLab, Linear Active Thermistor, Migratable Memory, MXDEV, MXLAB, PS logo, SEEVAL, SmartSensor and The Embedded Control Solutions Company are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Analog-for-the-Digital Age, Application Maestro, CodeGuard, dsPICDEM, dsPICDEM.net, dsPICworks, ECAN, ECONOMONITOR, FanSense, FlexROM, fuzzyLAB, In-Circuit Serial Programming, ICSP, ICEPIC, Mindi, MiWi, MPASM, MPLAB Certified logo, MPLIB, MPLINK, PICkit, PICDEM, PICDEM.net, PICLAB, PICtail, PowerCal, PowerInfo, PowerMate, PowerTool, REAL ICE, rfLAB, rfPICDEM, Select Mode, Smart Serial, SmartTel, Total Endurance, UNI/O, WiperLock and ZENA are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

 $\ensuremath{\mathsf{SQTP}}$ is a service mark of Microchip Technology Incorporated in the U.S.A.

All other trademarks mentioned herein are property of their respective companies.

© 2007, Microchip Technology Incorporated, Printed in the U.S.A., All Rights Reserved.

Printed on recycled paper.

QUALITY MANAGEMENT SYSTEM

CERTIFIED BY DNV

ISO/TS 16949:2002

Microchip received ISO/TS-16949:2002 certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona, Gresham, Oregon and Mountain View, California. The Company's quality system processes and procedures are for its PIC® MCUs and dsPIC® DSCs, KEELOQ® code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.



WORLDWIDE SALES AND SERVICE

AMERICAS

Corporate Office 2355 West Chandler Blvd.

Chandler, AZ 85224-6199 Tel: 480-792-7200 Fax: 480-792-7277 Technical Support:

http://support.microchip.com

Web Address: www.microchip.com

Atlanta

Duluth, GA Tel: 678-957-9614 Fax: 678-957-1455

Roston

Westborough, MA Tel: 774-760-0087 Fax: 774-760-0088

Chicago Itasca, IL

Tel: 630-285-0071 Fax: 630-285-0075

Dallas

Addison, TX Tel: 972-818-7423 Fax: 972-818-2924

Detroit

Farmington Hills, MI Tel: 248-538-2250 Fax: 248-538-2260

Kokomo

Kokomo, IN Tel: 765-864-8360 Fax: 765-864-8387

Los Angeles

Mission Viejo, CA Tel: 949-462-9523 Fax: 949-462-9608

Santa Clara

Santa Clara, CA Tel: 408-961-6444 Fax: 408-961-6445

Toronto

Mississauga, Ontario, Canada

Tel: 905-673-0699 Fax: 905-673-6509

ASIA/PACIFIC

Asia Pacific Office

Suites 3707-14, 37th Floor Tower 6, The Gateway Habour City, Kowloon Hong Kong

Tel: 852-2401-1200 Fax: 852-2401-3431

Australia - Sydney Tel: 61-2-9868-6733

Fax: 61-2-9868-6755 China - Beijing

Tel: 86-10-8528-2100 Fax: 86-10-8528-2104

China - Chengdu Tel: 86-28-8665-5511 Fax: 86-28-8665-7889

China - Fuzhou Tel: 86-591-8750-3506 Fax: 86-591-8750-3521

China - Hong Kong SAR Tel: 852-2401-1200

Fax: 852-2401-3431 China - Qingdao

Tel: 86-532-8502-7355 Fax: 86-532-8502-7205

China - Shanghai Tel: 86-21-5407-5533

Fax: 86-21-5407-5066

China - Shenyang Tel: 86-24-2334-2829 Fax: 86-24-2334-2393

China - Shenzhen Tel: 86-755-8203-2660

Fax: 86-755-8203-1760 China - Shunde

Tel: 86-757-2839-5507 Fax: 86-757-2839-5571

China - Wuhan Tel: 86-27-5980-5300 Fax: 86-27-5980-5118

China - Xian Tel: 86-29-8833-7250

Fax: 86-29-8833-7256

ASIA/PACIFIC

India - Bangalore

Tel: 91-80-4182-8400 Fax: 91-80-4182-8422

India - New Delhi

Tel: 91-11-4160-8631 Fax: 91-11-4160-8632

India - Pune

Tel: 91-20-2566-1512 Fax: 91-20-2566-1513

Japan - Yokohama Tel: 81-45-471- 6166

Fax: 81-45-471-6122 Korea - Gumi

Tel: 82-54-473-4301 Fax: 82-54-473-4302

Korea - Seoul Tel: 82-2-554-7200 Fax: 82-2-558-5932 or 82-2-558-5934

Malaysia - Penang Tel: 60-4-646-8870 Fax: 60-4-646-5086

Philippines - Manila Tel: 63-2-634-9065

Fax: 63-2-634-9069

Singapore

Tel: 65-6334-8870 Fax: 65-6334-8850 Taiwan - Hsin Chu

Tel: 886-3-572-9526 Fax: 886-3-572-6459

Taiwan - Kaohsiung Tel: 886-7-536-4818 Fax: 886-7-536-4803

Taiwan - Taipei Tel: 886-2-2500-6610 Fax: 886-2-2508-0102

Thailand - Bangkok Tel: 66-2-694-1351 Fax: 66-2-694-1350

EUROPE

Austria - Wels

Tel: 43-7242-2244-39 Fax: 43-7242-2244-393

Denmark - Copenhagen

Tel: 45-4450-2828 Fax: 45-4485-2829

France - Paris

Tel: 33-1-69-53-63-20 Fax: 33-1-69-30-90-79

Germany - Munich

Tel: 49-89-627-144-0 Fax: 49-89-627-144-44

Italy - Milan

Tel: 39-0331-742611 Fax: 39-0331-466781

Netherlands - Drunen Tel: 31-416-690399

Fax: 31-416-690340 Spain - Madrid

Tel: 34-91-708-08-90 Fax: 34-91-708-08-91

UK - Wokingham Tel: 44-118-921-5869 Fax: 44-118-921-5820

12/08/06